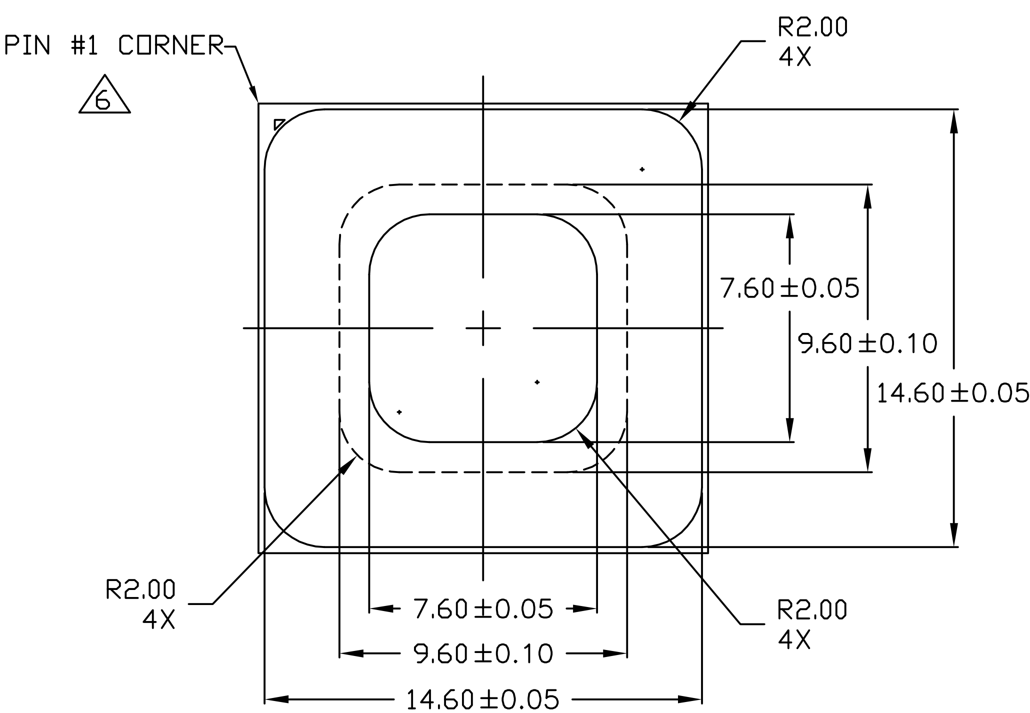
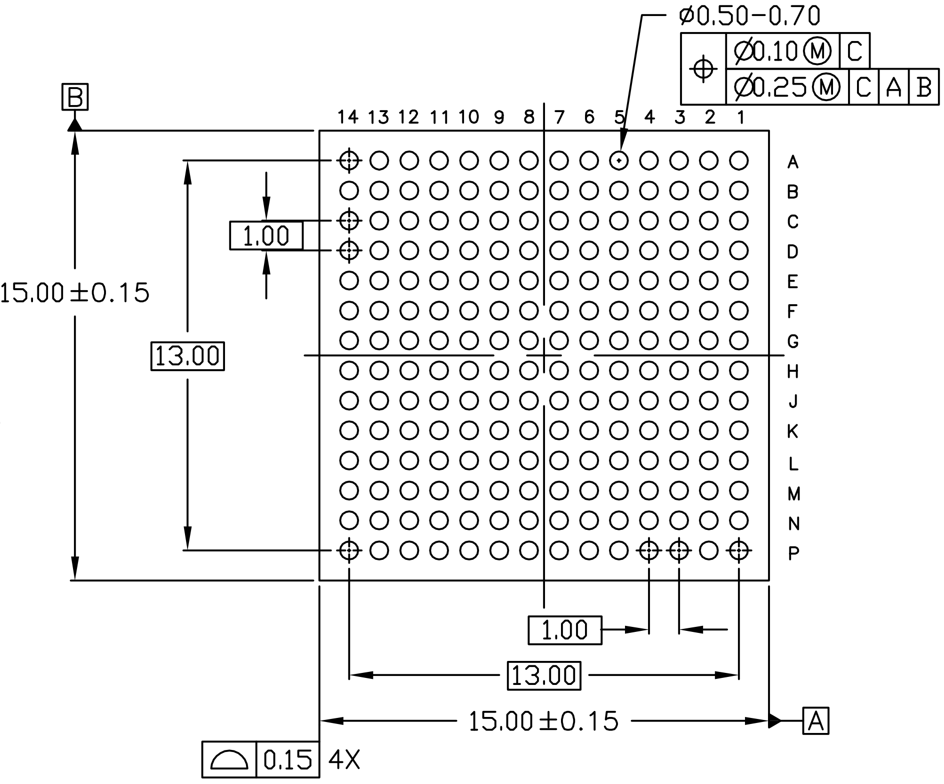
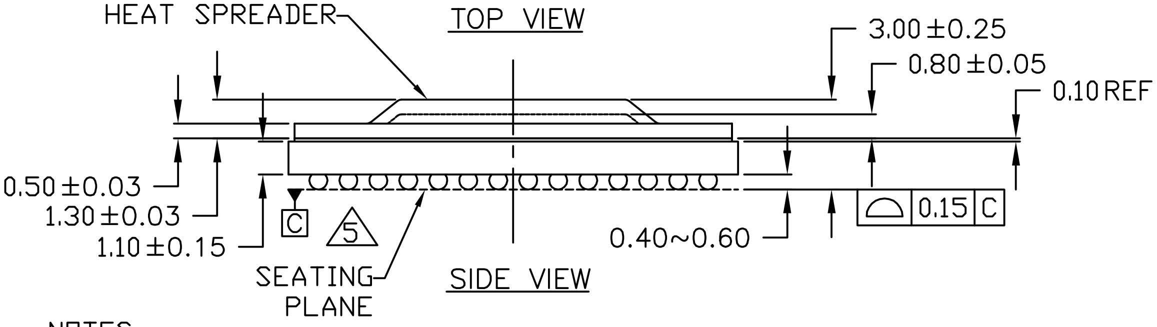


TOP VIEW



BOTTOM VIEW



SIDE VIEW

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. MATERIAL MUST COMPLY WITH BANNED AND RESTRICTED SUBSTANCES SPEC #10-0131.
3. THE BASIC SOLDER BALL GRID PITCH IS 1.00 MM AND BALL DIA IS 0.60 MM.
4. SUBSTRATE THICKNESS IS 1.10 MM.
5. PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
6. A1 BALL PAD CORNER I.D.
7. ALL DIMENSIONS APPLY TO BOTH LEADED (-), LEADFREE (+), AND ROHS EXEMPT (#) PKG. CODES.
8. PACKAGE CODES: X196FH-1, X19655FH-3

-DRAWING NOT TO SCALE-

TITLE:
PACKAGE OUTLINE, 196 BALLS HSBGAF,
15x15X3.00mm, 6 LAYER, 1.00mm PITCH

APPROVAL	DOCUMENT CONTROL NO.	REV.	
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